



Material Content Data Sheet



Sales Product Name		ICE3B0365J		Issued		20. July 2018		
MA#		MA001609382						
Package		PG-DIP-8-15		Weight*		550.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.248	0.41	0.41	4083	4083
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		97	
	non noble metal	zinc	7440-66-6	0.213	0.04		387	
	non noble metal	iron	7439-89-6	4.266	0.77		7748	
wire	non noble metal	copper	7440-50-8	173.237	31.46	32.28	314618	322850
	noble metal	gold	7440-57-5	0.419	0.08	0.08	761	761
	encapsulation	organic material	carbon black	1333-86-4	1.802	0.33		3273
encapsulation	plastics	epoxy resin	-	48.660	8.84		88373	
	inorganic material	silicondioxide	60676-86-0	309.985	56.28	65.45	562965	654611
leadfinish	non noble metal	tin	7440-31-5	7.496	1.36	1.36	13613	13613
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1454	1454
glue	plastics	epoxy resin	-	0.253	0.05		460	
	noble metal	silver	7440-22-4	1.194	0.22	0.27	2168	2628
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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